

CLAIMS

1. A method of manufacturing a multilayer circuit board,
in which a plurality printed board are stacked and pressed into
5 a multilayer circuit board, each printed board having a conductor
layer on one side of an insulating layer, characterized by the
steps of stacking the printed boards with a bonding layer being
interposed between the printed boards, and stacking an outermost
conductor layer on an insulating layer side of a first outermost
10 printed board with a bonding layer being interposed therebetween
and pressing a stack so that the printed boards and the outermost
conductor layer are bonded together, the first outermost printed
board being disposed with the insulating layer side being directed
outward.

15

2. A method of manufacturing according to claim 1,
characterized in that the printed boards include a second
outermost printed board disposed with a conductor layer side being
directed outward, the conductor layer being pressed under a
20 condition where the conductor layer has a uniform thickness all
over.